



Material Content Data Sheet



Sales Product Name	BBY 66-02V H6327				Issued		16. January 2020	
MA#	MA000791204							
Package	PG-SC79-2-1				Weight*		1.68 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	arsenic	7440-38-2	0.000	0.00		32	
	noble metal	gold	7440-57-5	0.005	0.32		3181	
	inorganic material	silicon	7440-21-3	0.046	2.72	3.04	27164	30377
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		92	
	non noble metal	titanium	7440-32-6	0.001	0.05		458	
	non noble metal	chromium	7440-47-3	0.002	0.14		1375	
	non noble metal	copper	7440-50-8	0.767	45.62	45.82	456381	458306
wire	non noble metal	copper	7440-50-8	0.007	0.41	0.41	4056	4056
encapsulation	organic material	carbon black	1333-86-4	0.007	0.42		4223	
	plastics	epoxy resin	-	0.121	7.18		71789	
	inorganic material	silicondioxide	60676-86-0	0.582	34.63	42.23	346276	422288
leadfinish	non noble metal	tin	7440-31-5	0.055	3.25	3.25	32463	32463
plating	noble metal	silver	7440-22-4	0.088	5.25	5.25	52510	52510
*deviation	< 10%	Sum in total:			100.00			1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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